Product Information Sheet

EPO-TEK® E3037-LV

Date:	September 2017
Rev:	II
No. of Components:	Single
Mix Ratio by Weight:	N/A
Specific Gravity:	2.85
Pot Life:	21 Days
Shelf Life- Bulk:	One year at -40°C

Recommended Cure: 150°C / 1 Hour

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, silver-filled and electrically conductive adhesive designed for semiconductor die attach and bonding of SMDs for hybrid microelectronic packaging.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Silver		
* Consistency:	Smooth flowing paste		
* Viscosity (23°C) @ 10 rpm:	9,500 - 17,500	cPs	
Thixotropic Index:	2.9		
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	35	x 10^{-6} in/in°C	
Above Tg:	122	x 10^{-6} in/in°C	
Shore D Hardness:	73		
Lap Shear @ 23°C:	1,968	psi	
Die Shear @ 23°C:	≥ 5	Kg	1,778 psi
Degradation Temp:	342	°C	
Weight Loss:			
@ 200°C:	0.16	%	
@ 250°C:	0.25	%	
@ 300°C:	0.32	%	
Suggested Operating Temperature:	< 275	°C (Intermittent)	
Storage Modulus:	623,152	psi	
Ion Content:	Cl^-: 172 ppm		
	NH_4^+: 65 ppm	K^+:	45 ppm
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	0.7	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0005	Ohm-cm

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